

REMARKS

The previous claims have been replaced with new claims 44-53. The new claims are directed to a pressure sensitive adhesive sheet with a release sheet that is particularly suitable for use for electrical and electronic equipment such as hard disks. As pointed out in the specification, when such a pressure sensitive adhesive sheet is used, it must not emit silicone compounds. Further, because most electrical and electronic equipment is assembled and manufactured in clean rooms, the pressure sensitive adhesive sheet must also prevent generation of dust (particles) when it is used. In this regard, when such pressure sensitive adhesive sheets are used in clean rooms, the release sheets are peeled off from the pressure sensitive adhesive sheets just before they are used. Therefore, it is very important for such a pressure sensitive adhesive sheet with a release sheet to reduce dust (particles) generated from the release sheet when it is peeled off from the pressure sensitive adhesive sheet so that the generation of the amount particles is as small as possible.

In order to satisfy both of these requirements for pressure sensitive adhesive sheets with a release sheet for use with electrical and electronic equipment, the present invention uses a lint-free paper having a thickness of 25 to 50 μm as a material of the release sheet base of the release sheet. By using such a thin lint-free paper as a material for the release sheet base, less dust (particles) is generated when it is peeled off from the pressure sensitive adhesive sheet. Further, the lint-free paper is also suitable for the releasing agent layer containing no silicone compound since reliable adhesion can be obtained between the lint-free paper and the releasing agent layer. In

other words, the particle count parameter defined in claim 44 mainly results from the use of such a thin lint-free paper as a material for the release sheet base.

In contrast, neither JP-A-08-245932 nor Meyer disclose or suggest these features of the presently claimed invention. For example, JP-A-08-245932 and Meyer do not disclose or teach use of such a thin lint-free paper having a thickness of 25 to 50 μm as a base material of the release sheet. Further, these references do not suggest or teach the possible combination of such a very thin lint-free sheet and the releasing agent layer containing substantially no silicone compound.

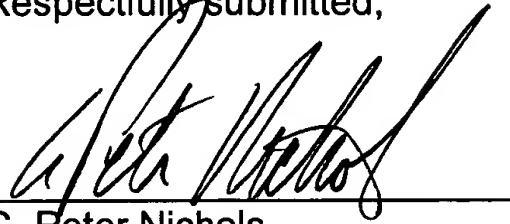
Further, these references do not disclose or teach the count of the generated particles and the measuring method thereof defined in present claim 44. In fact, Meyer does not teach or suggest the relationship between the base material of the release sheet base (that is, extremely thin lint-free paper) and the count of generated particles, or the specific value of the count of generated particles defined in present claim 44. In this regard, it is to be noted that the measuring method described in the Semiconductor Production Apparatus and Material International Associate Doc. No. 2362 (which is described in page 47 of the specification of this application) is now called the measuring method of "TEST METHOD for the Measurement of Particle Generation from Sheet Materials determined by SEMI G67-0996". Further, please note that Semiconductor Production Apparatus and Material International Associate was changed into Semiconductor Equipment and Material International (SEMI).

It is believed that all the claims are in condition to be allowed and notification to that effect is requested. If, for any reason, the Examiner feels that the above amendments and remarks do not put the claims in condition for allowance, the

undersigned attorney can be reached at (312) 321-4276 to resolve any remaining issues.

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Respectfully submitted,

A handwritten signature in black ink, appearing to read 'G. Peter Nichols', is written over a horizontal line.

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